Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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SMPS MOSFET

PD - 95293

International
IOR Rectifier

IRF6216PbF

HEXFET® Power MOSFET

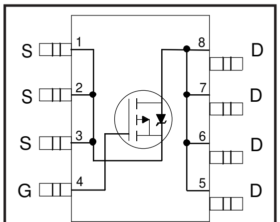
V_{DSS}	$R_{DS(on)}$ max	I_D
-150V	0.240Ω@V_{GS} =-10V	-2.2A

Applications

- Reset Switch for Active Clamp Reset DC-DC converters
- Lead-Free

Benefits

- Low Gate to Drain Charge to Reduce Switching Losses
- Fully Characterized Capacitance Including Effective C_{OSS} to Simplify Design (See App. Note AN1001)
- Fully Characterized Avalanche Voltage and Current



Top View


SO-8

Absolute Maximum Ratings

	Parameter	Max.	Units
I_D @ T_A = 25°C	Continuous Drain Current, V_{GS} @ 10V	-2.2	A
I_D @ T_A = 70°C	Continuous Drain Current, V_{GS} @ 10V	-1.9	
I_{DM}	Pulsed Drain Current ①	-19	
P_D @T_A = 25°C	Power Dissipation④	2.5	W
	Linear Derating Factor	0.02	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
dv/dt	Peak Diode Recovery dv/dt	7.8	V/ns
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 150	°C
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	

Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JL}$	Junction-to-Drain Lead	——	20	°C/W
$R_{\theta JA}$	Junction-to-Ambient ④	——	50	

Notes ① through ④ are on page 8

06/06/05

Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-150	—	—	V	V_{GS} = 0V, I_D = -250µA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	-0.17	—	V/°C	Reference to 25°C, I_D = -1mA ③
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.240	Ω	V_{GS} = -10V, I_D = -1.3A ③
$V_{GS(th)}$	Gate Threshold Voltage	-3.0	—	-5.0	V	V_{DS} = V_{GS}, I_D = -250µA
I_{DSS}	Drain-to-Source Leakage Current	—	—	-25	µA	V_{DS} = -150V, V_{GS} = 0V
		—	—	-250		V_{DS} = -120V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Forward Leakage	—	—	-100	nA	V_{GS} = -20V
	Gate-to-Source Reverse Leakage	—	—	100		V_{GS} = 20V

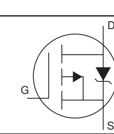
Dynamic @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
g_{fs}	Forward Transconductance	2.7	—	—	S	V_{DS} = -50V, I_D = -1.3A
Q_g	Total Gate Charge	—	33	49	nC	I_D = -1.3A
Q_{gs}	Gate-to-Source Charge	—	7.2	11		V_{DS} = -120V
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	15	23		V_{GS} = -10V,
$t_{d(on)}$	Turn-On Delay Time	—	18	—	ns	V_{DD} = -75V
t_r	Rise Time	—	15	—		I_D = -1.3A
$t_{d(off)}$	Turn-Off Delay Time	—	33	—		R_G = 6.5Ω
t_f	Fall Time	—	26	—		V_{GS} = -10V ③
C_{iss}	Input Capacitance	—	1280	—	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	—	220	—		V_{DS} = -25V
C_{rss}	Reverse Transfer Capacitance	—	53	—		ƒ = 1.0MHz
C_{oss}	Output Capacitance	—	1290	—		V_{GS} = 0V, V_{DS} = -1.0V, ƒ = 1.0MHz
C_{oss}	Output Capacitance	—	99	—		V_{GS} = 0V, V_{DS} = -120V, ƒ = 1.0MHz
C_{oss} eff.	Effective Output Capacitance	—	220	—		V_{GS} = 0V, V_{DS} = 0V to -120V

Avalanche Characteristics

	Parameter	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy②	—	200	mJ
I_{AR}	Avalanche Current①	—	-4.0	A

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-2.2	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	-19		
V_{SD}	Diode Forward Voltage	—	—	-1.6	V	T_J = 25°C, I_S = -1.3A, V_{GS} = 0V ③
t_{rr}	Reverse Recovery Time	—	80	120	nS	T_J = 25°C, I_F = -1.3A
Q_{rr}	Reverse RecoveryCharge	—	310	460	nC	di/dt = -100A/µs ③

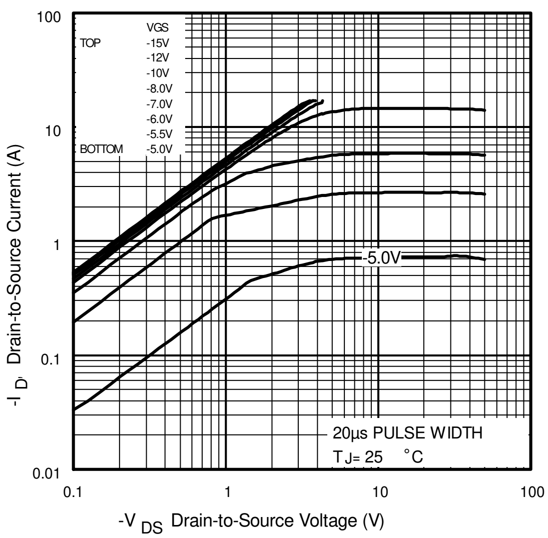


Fig 1. Typical Output Characteristics

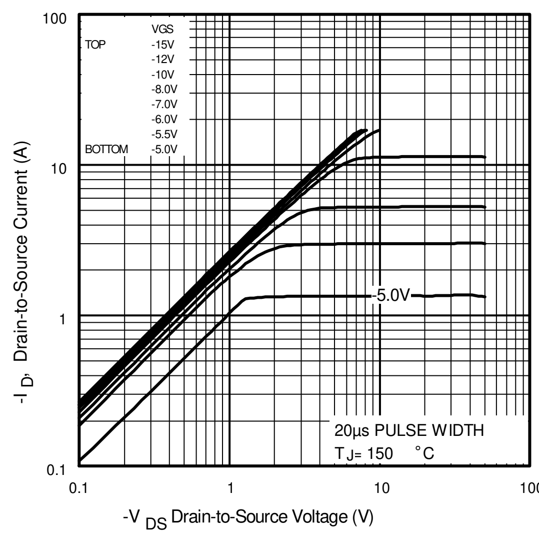


Fig 2. Typical Output Characteristics

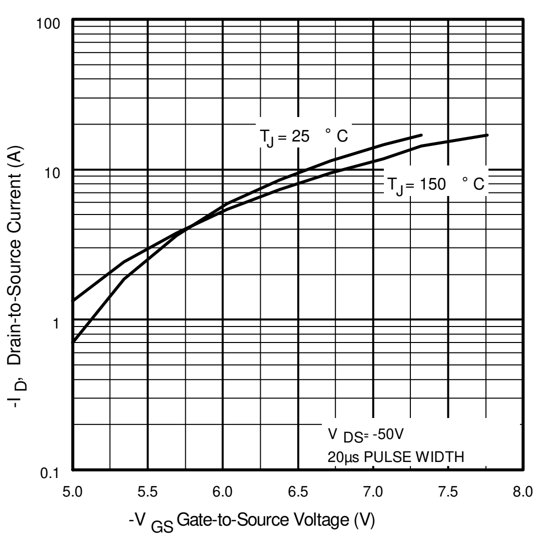


Fig 3. Typical Transfer Characteristics

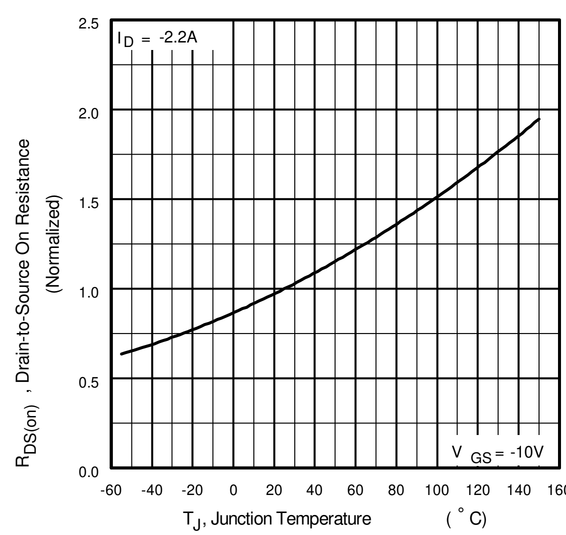


Fig 4. Normalized On-Resistance
Vs. Temperature

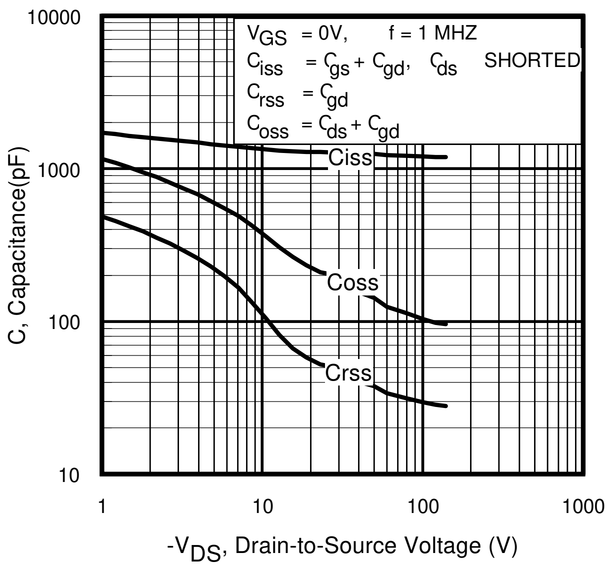


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

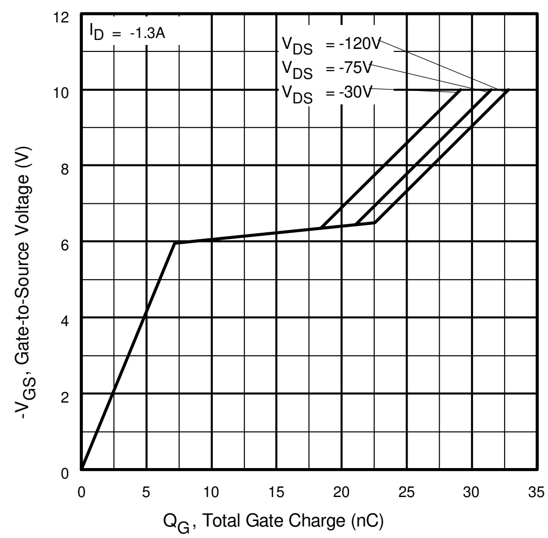


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

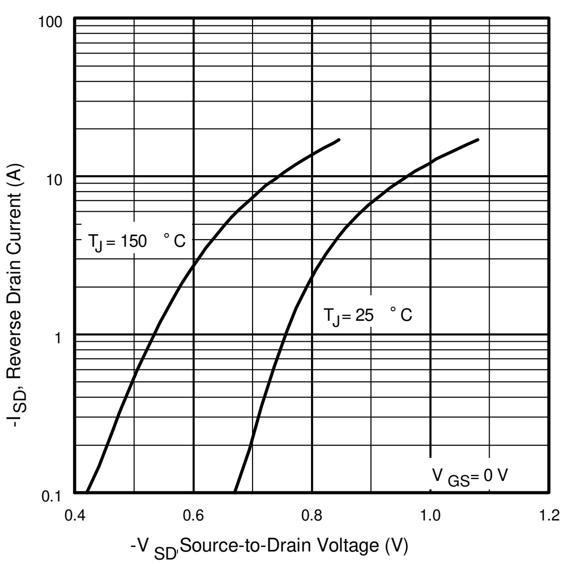


Fig 7. Typical Source-Drain Diode Forward Voltage

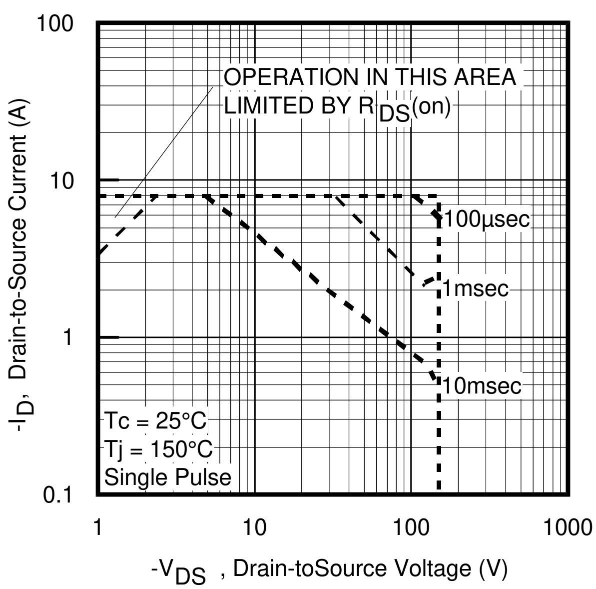


Fig 8. Maximum Safe Operating Area

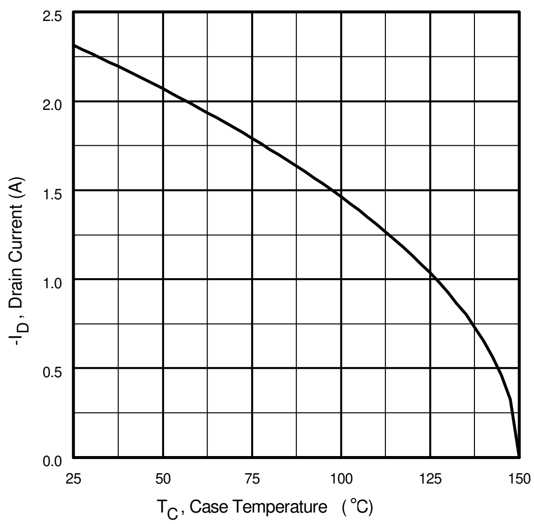


Fig 9. Maximum Drain Current Vs. Ambient Temperature

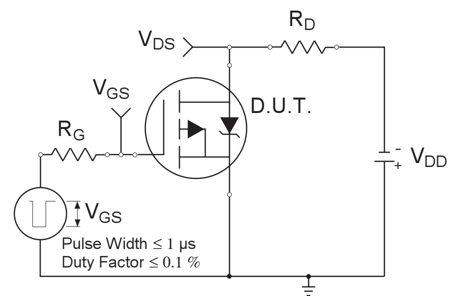


Fig 10a. Switching Time Test Circuit

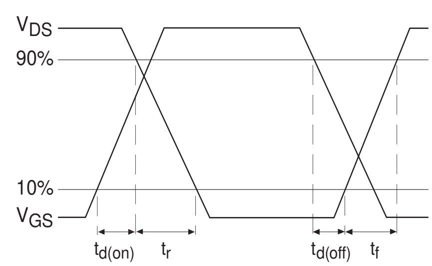


Fig 10b. Switching Time Waveforms

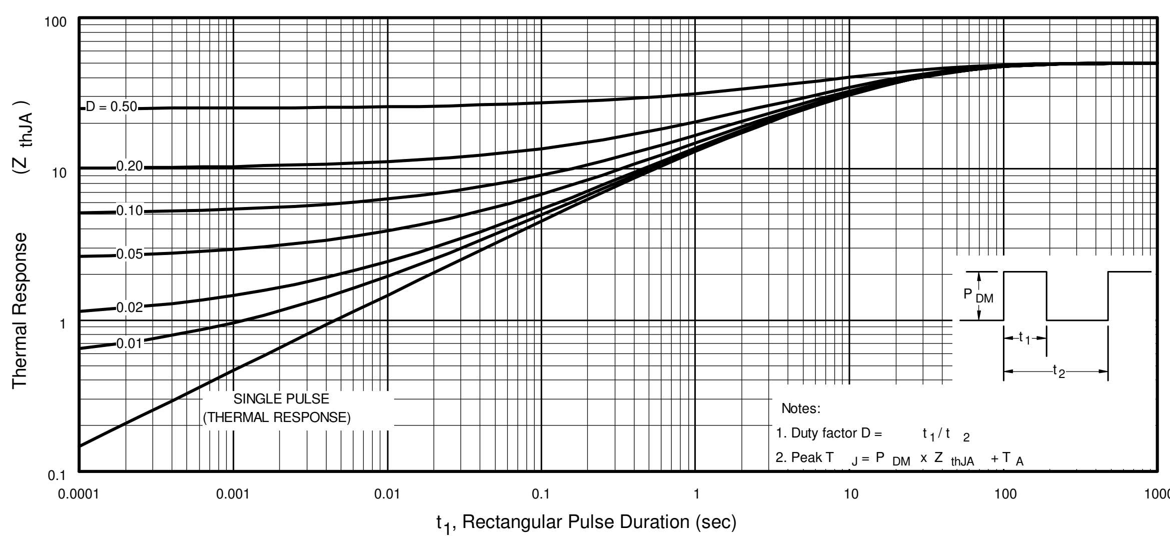


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

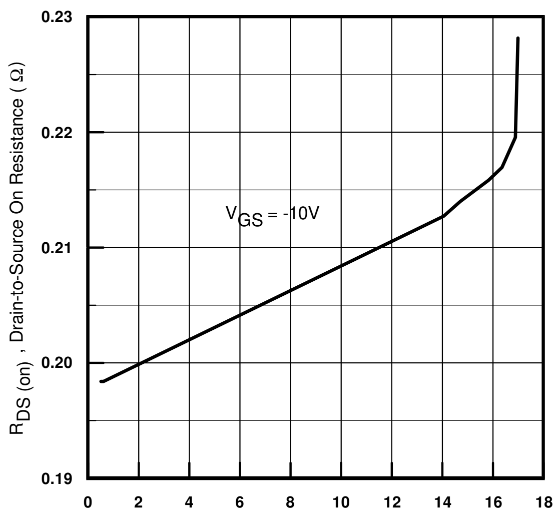


Fig 12. On-Resistance Vs. Drain Current

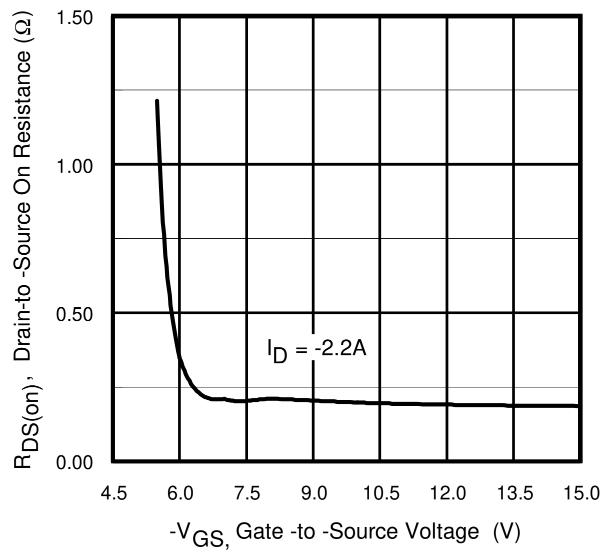


Fig 13. On-Resistance Vs. Gate Voltage

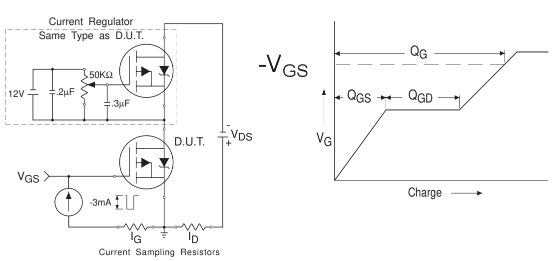


Fig 14a&b. Basic Gate Charge Test Circuit and Waveform

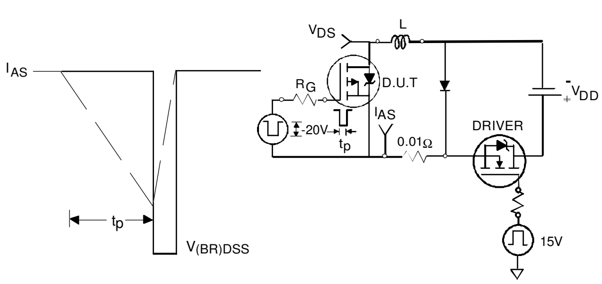


Fig 15a&b. Unclamped Inductive Test circuit and Waveforms

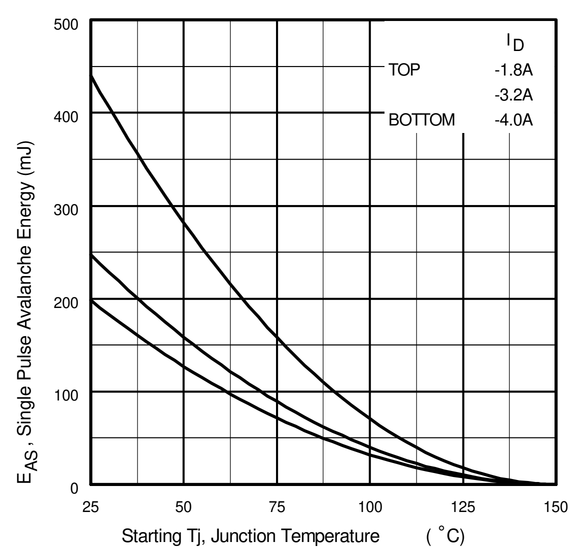
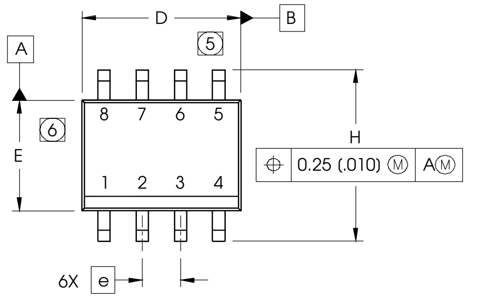


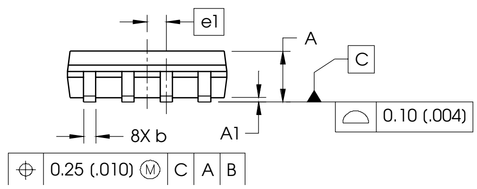
Fig 15c. Maximum Avalanche Energy Vs. Drain Current

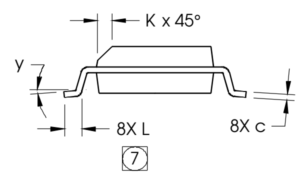
SO-8 Package Outline

Dimensions are shown in millimeters (inches)



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e 1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°





NOTES:

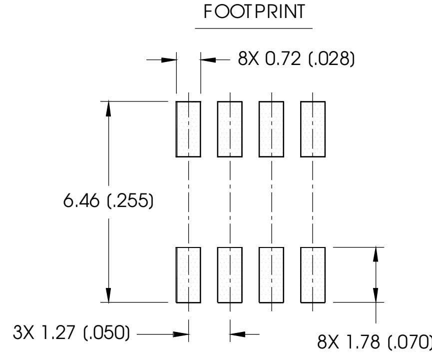
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.

5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 (.006).

6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.010).

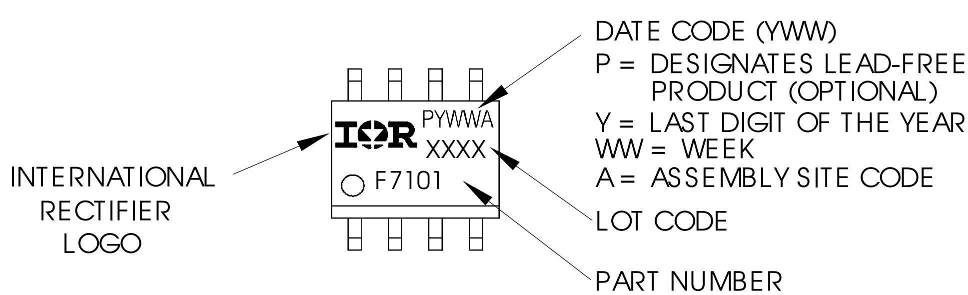
7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

FOOTPRINT



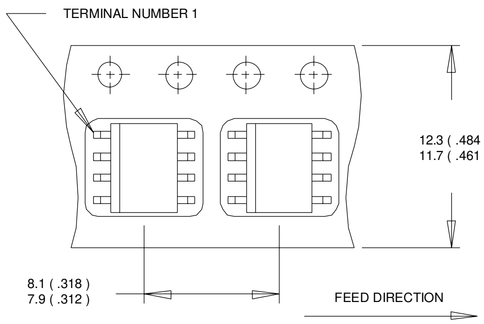
SO-8 Part Marking

EXAMPLE: THIS IS AN IRF7101 (MOSFET)

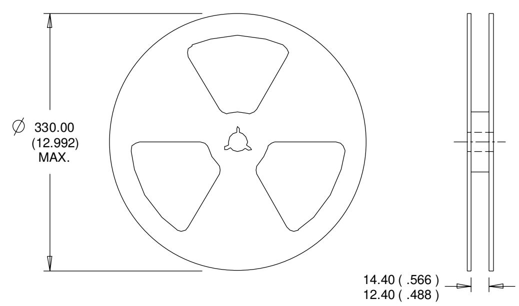


SO-8 Tape and Reel

Dimensions are shown in millimeters (inches)



NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Notes:

① Repetitive rating; pulse width limited by max. junction temperature.

② Starting $T_J = 25°C$, L = 25mH $R_G = 25\Omega$, $I_{AS} = -4.0A$.

③ Pulse width ≤ 400µs; duty cycle ≤ 2%.

④ When mounted on 1 inch square copper board.

Data and specifications subject to change without notice.
This product has been designed and qualified for the Consumer market.
Qualifications Standards can be found on IR's Web site.

International Rectifier

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